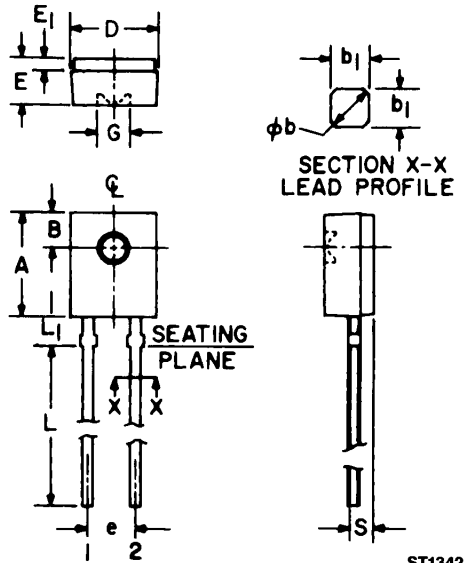


#### PACKAGE DIMENSIONS



ST1342

#### DESCRIPTION

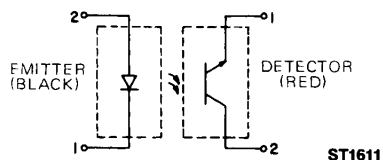
The H23A is a matched emitter-detector pair which consists of a gallium arsenide infrared emitting diode and a silicon phototransistor. The clear epoxy packaging system is designed to optimize the mechanical resolution, coupling efficiency, cost, and reliability. The devices are marked with a color dot for easy identification of the emitter and detector.

#### FEATURES

- Good optical to mechanical alignment
- Color dot for easy recognition of LED and phototransistor
- Low cost

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	5.59	5.80	.220	.228	
B	1.78	NOM.	.070	NOM.	2
@b	.60	.75	.024	.030	1
b.	.51	NOM.	.020	NOM.	1
D	4.45	4.70	.175	.185	
E	2.41	2.67	.095	.105	
E <sub>1</sub>	.58	.69	.023	.027	
e	2.41	2.67	.095	.105	3
G	1.98	NOM.	.078	NOM.	
L	12.7	—	.500	—	
L <sub>1</sub>	1.40	1.65	.055	.065	
S	.83	.94	.033	.037	3

#### PACKAGE OUTLINE



ST1611

#### NOTES

1. TWO LEADS. LEAD CROSS SECTION DIMENSIONS UNCONTROLLED WITHIN 1.27 mm (0.50") OF SEATING PLANE.
2. CENTERLINE OF ACTIVE ELEMENT LOCATED WITHIN .25 mm (.010") OF TRUE POSITION.
3. AS MEASURED AT THE SEATING PLANE.
4. INCH DIMENSIONS DERIVED FROM MILLIMETERS.

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_A = 25^\circ\text{C}$ Unless Otherwise Specified)	
Storage Temperature .....	$-55^\circ\text{C}$ to $+100^\circ\text{C}$
Operating Temperature .....	$-55^\circ\text{C}$ to $+100^\circ\text{C}$
Soldering:	
Lead Temperature (Iron) .....	$240^\circ\text{C}$ for 5 sec. <sup>(3,4,5)</sup>
Lead Temperature (Flow) .....	$260^\circ\text{C}$ for 10 sec. <sup>(3,4,5)</sup>
<b>INPUT DIODE</b>	
Continuous Forward Current .....	60 mA
Forward Current (pw, $1\mu\text{S}$ ; 33 Hz) .....	3 A
Reverse Voltage .....	6.0 Volts
Power Dissipation .....	100mW <sup>(1)</sup>
<b>OUTPUT TRANSISTOR</b>	
Collector-Emitter Voltage .....	30 Volts
Emitter-Collector Voltage .....	6 Volts
Power Dissipation .....	150 mW <sup>(2)</sup>

<b>ELECTRICAL CHARACTERISTICS</b> ( $T_A = 25^\circ\text{C}$ Unless Otherwise Specified)						
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS
<b>INPUT DIODE</b>						
Forward Voltage	$V_F$	—		1.7	V	$I_F = 60\text{ mA}$
Reverse Leakage Current	$I_R$	—		10	$\mu\text{A}$	$V_R = 6\text{V}$
Reverse Breakdown Voltage	$BV_R$	6.0		—	V	$I_R = 10\mu\text{A}$
<b>OUTPUT TRANSISTOR</b>						
Emitter-Collector Breakdown	$BV_{ECO}$	6.0		—	V	$I_E = 100\mu\text{A}$
Collector-Emitter Breakdown	$BV_{CEO}$	30		—	V	$I_C = 10\text{ mA}$
Collector-Emitter Leakage	$I_{CEO}$	—		100	nA	$V_{CE} = 10\text{ V}$
<b>COUPLED</b>						
On-State Collector Current	$I_{C(ON)}$		See page 3.			
Saturation Voltage	$V_{CE(SAT)}$		See page 3.			
Turn-On Time	$t_{on}$		150		$\mu\text{S}$	$I_F = 30\text{ mA}$ , $V_{CC} = 5\text{V}$ $R_L = 2.5\text{K}\Omega$
Turn-Off Time	$t_{off}$		150		$\mu\text{S}$	$I_F = 30\text{ mA}$ , $V_{CC} = 5\text{V}$ $R_L = 2.5\text{K}\Omega$

<b>NOTES</b>
1. Derate power dissipation linearly 1.33mW/°C above 25°C.
2. Derate power dissipation linearly 2.00mW/°C above 25°C.
3. RMA flux is recommended.
4. Methanol or Isopropyl alcohols are recommended as cleaning agents.
5. Soldering iron tip 1/16" (1.6 mm) minimum from housing.
6. Coupled characteristics are measured at a separation distance of .155" (4 mm) with the lenses of the emitter and detector on a common axis within 0.1mm and parallel within 5°.



**PLASTIC SIDELOOKER PAIR**

**H23A1/2**

<b><math>I_{C(ON)}</math> and <math>V_{CE(SAT)}</math> TABLE</b>						
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS
<b>ON-STATE COLLECTOR CURRENT</b>						
H23A1	$I_{C(ON)}$	1.5	—	—	mA	$I_F = 30\text{mA}, V_{CE} = 5\text{V}^{(6)}$
H23A2	$I_{C(ON)}$	0.5	—	—	mA	$I_F = 30\text{mA}, V_{CE} = 5\text{V}^{(6)}$
<b>SATURATION VOLTAGE</b>						
H23A1	$V_{CE(SAT)}$	—	—	0.40	V	$I_F = 30\text{mA}, I_C = 1.0\text{mA}^{(6)}$
H23A2	$V_{CE(SAT)}$	—	—	0.40	V	$I_F = 30\text{mA}, I_C = .4\text{mA}^{(6)}$

### TYPICAL CHARACTERISTICS

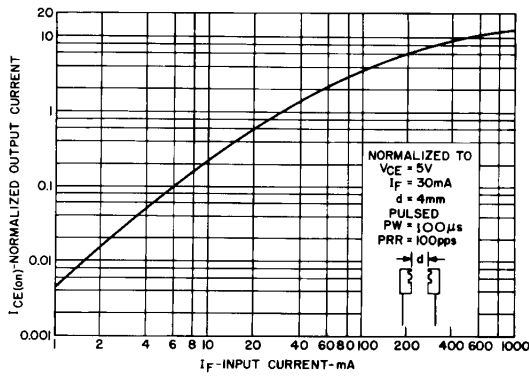


Fig. 1. Output Current vs. Input Current

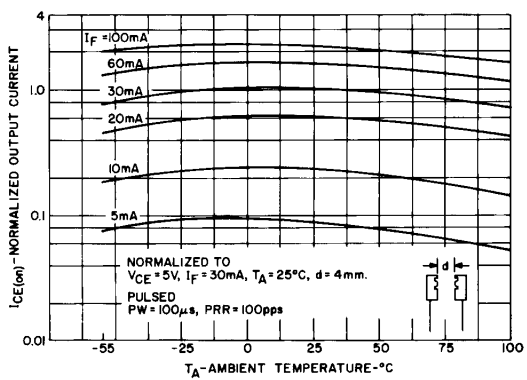


Fig. 2. Output Current vs. Temperature

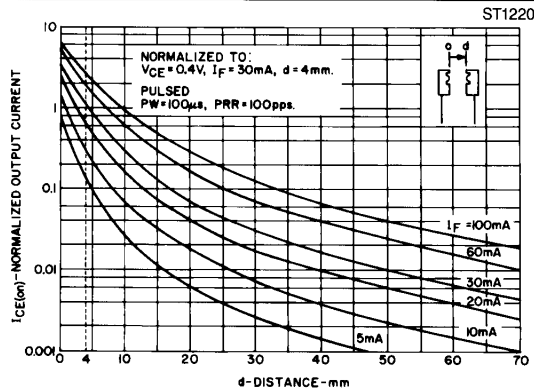


Fig. 3. Output Current vs. Distance

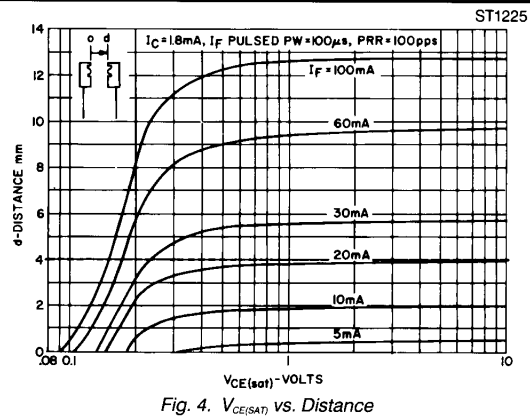


Fig. 4.  $V_{CE(SAT)}$  vs. Distance

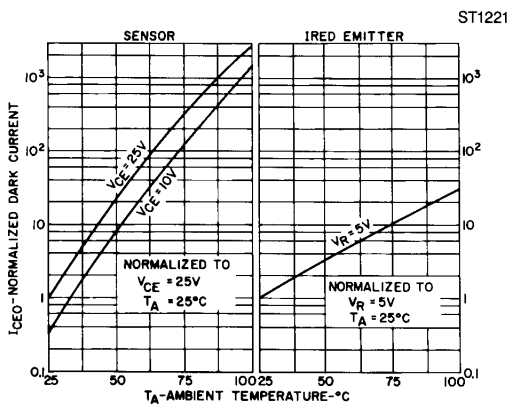


Fig. 5. Leakage Currents vs. Temperature

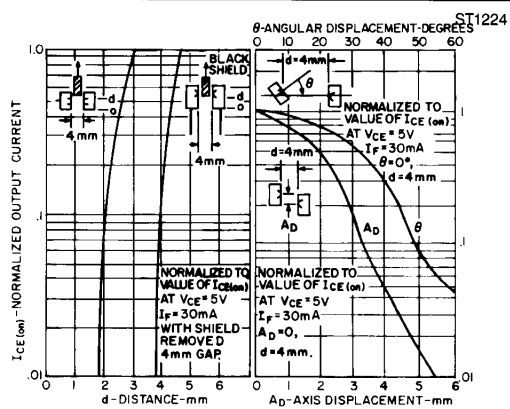


Fig 6A. Output Current vs. Shield Distance

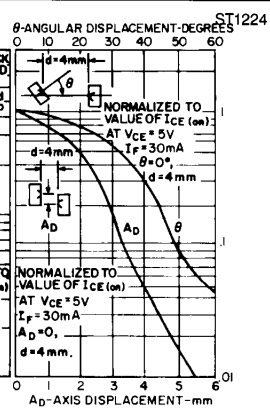


Fig 6B. Output Current vs. Displacement (Angular & Axis)

ST1222

ST1223



## PLASTIC SIDELOOKER PAIR

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.